

NLX-6 BLUE POWER DIE

BXCD 50 mil x 50 mil

PRODUCT DATA SHEET DS-C11

The Bridgelux NLX-6 family of blue power die enables high performance and cost effective solutions to serve solid state lighting market. This next generation chip output for a variety of lighting, signaling and display applications.

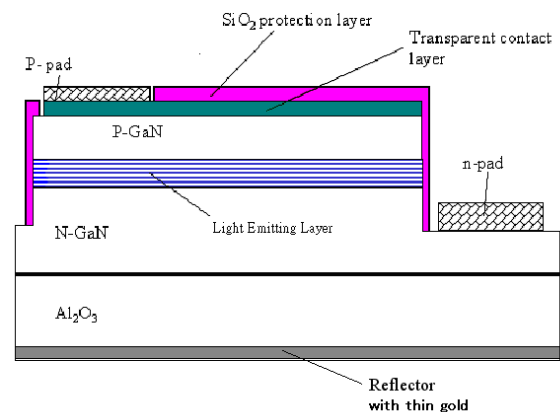
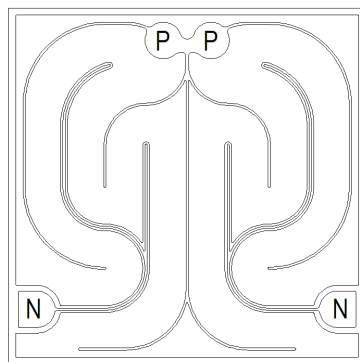
Features

- High lumen output and efficiency
- Long operating life
- 100% Tested and sorted by wavelength, power and forward voltage
- Lambertian emission pattern
- Compatible with Solder paste, solder preform or silver epoxy die attach
- Delivered on medium tack blue tape (20cm±10mm x20 cm±10mm)

Applications

- General Illumination
- Portable Lighting
- Architectural Lighting
- Directional Lighting
- Display Backlighting
- Digital Camera Flash
- Automotive Lighting
- White LEDs

LED Chip Diagram



(Note: drawing is not to scale)

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Mechanical Dimensions

Chip Size	1270 ^{+30/-10} μm x 1270 ^{+30/-10} μm (50 mil x 50 mil)
Chip Thickness	150 \pm 10 μm (5.9 mil)
Au Pad Thickness	4.4 \pm 0.3 μm
Au Pad Diameter	P Pad: 130 μm N Pad: 130 μm

Absolute Maximum Ratings

Parameter	Symbol	Maximum Rating	Condition
DC Forward Current	I_f	700 mA ¹	$T_j = 140^\circ\text{C}$
Junction Temperature	T_j	150 $^\circ\text{C}$	
Reverse Voltage	V_r	-5 V	$T_a = 25^\circ\text{C}$
Reverse Current	I_r	< 10 μA	$V_r = -5\text{ V}$
Assembly Process Temperature		325 $^\circ\text{C}$ for < 5 seconds	
Storage Conditions (chip on tape) ⁶		0 $^\circ\text{C}$ to +40 $^\circ\text{C}$ ambient, RH < 65%	

Notes:

1. Maximum drive current depends on junction temperature, die attach methods/materials, and lifetime requirements of the application.
2. Bridgelux LED chips are Class 1 ESD sensitive.
3. The typical spectra half-width of the NLX-6 blue power die is < 25 nm.
4. Please consult the Bridgelux technical support team for information on how to optimize the light output of our chips in your package.
5. Brightness values are measured in an integrating sphere using gold plated TO39 headers without encapsulation.
6. Tapes should be stored in a vertical orientation, not horizontally stacked. Stacking of tapes can place excessive pressure on the bond pads of the LED, resulting in reduced wire bonding strength.

Environmental Compliance

Bridgelux is committed to providing environmentally friendly products to the solid state lighting market. Bridgelux NLX-6 blue power die are compliant to the European Union directives on the restriction of hazardous substances in electronic equipment, namely the RoHS directive. Bridgelux will not intentionally add the following restricted materials to NLX-6 die products: lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE).

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Part Numbering and Bin Definitions

Bridgelux LED chips are sorted into the brightness and dominant wavelength bins shown below at $I_f = 350$ mA. Each blue tape contains die from only one brightness bin and one wavelength bin.

Each blue tape contains chips with 0.2 V forward voltage bins: 3.0 - 3.2 V, 3.2 - 3.4 V and 3.4 - 3.6 V. The typical forward voltage is 3.2 V and the maximum forward voltage ($V_f \text{ max}$) = 3.6 V.

Dominant Wavelength	Power Bin D2 (275 – 295 mW)	Power Bin E1 (295 – 320 mW)	Power Bin E2 (320 – 340 mW)
445 to 447.5nm	BXCD5050445-D2-z	BXCD5050445-E1-z	BXCD5050445-E2-z
447.5 to 450nm	BXCD5050447-D2-z	BXCD5050447-E1-z	BXCD5050447-E2-z
450 to 452.5nm	BXCD5050450-D2-z	BXCD5050450-E1-z	BXCD5050450-E2-z
452.5 to 455nm	BXCD5050452-D2-z	BXCD5050452-E1-z	BXCD5050452-E2-z
455 to 457.5nm	BXCD5050455-D2-z	BXCD5050455-E1-z	BXCD5050455-E2-z
457.5 to 460nm	BXCD5050457-D2-z	BXCD5050457-E1-z	BXCD5050457-E2-z
460 to 462.5nm	BXCD5050460-D2-z	BXCD5050460-E1-z	BXCD5050460-E2-z
462.5 to 465nm	BXCD5050462-D2-z	BXCD5050462-E1-z	BXCD5050462-E2-z

Product Nomenclature

B X C D 5 0 5 0 X X X – Y – Z

Where:

- BXCD: Designates product family
- 5050: Designates die size (50 mil x 50 mil)
- XXX: Designates dominant wavelength bin
- Y: Designates radiometric power bin
- Z: Designates forward voltage bin

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Performance vs. Current

The following curves represent typical performance of the BXCD NLX-6 blue power die. Actual performance will vary slightly for different power and dominant wavelength bins.

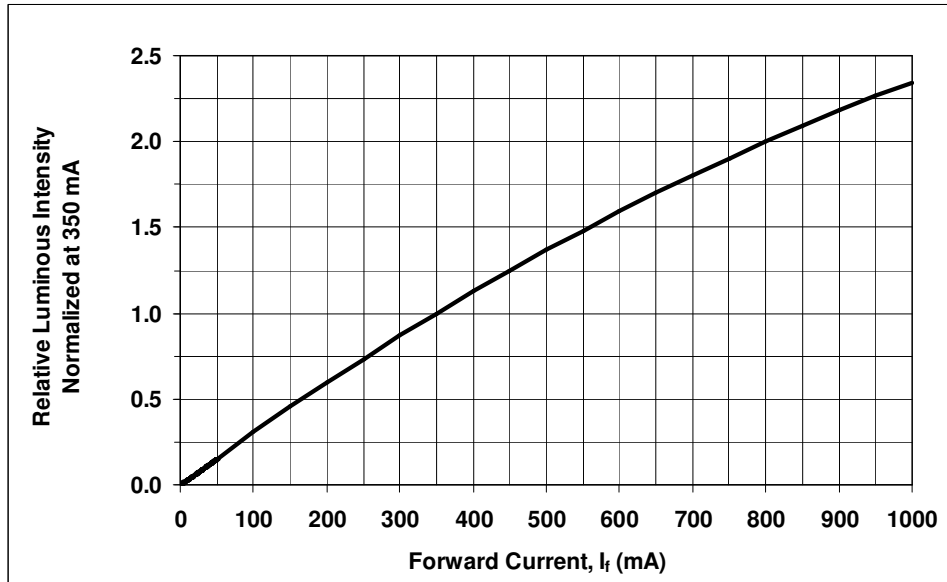


Figure 1: Relative Luminous Intensity vs. Forward Current (device tested on a probe station)

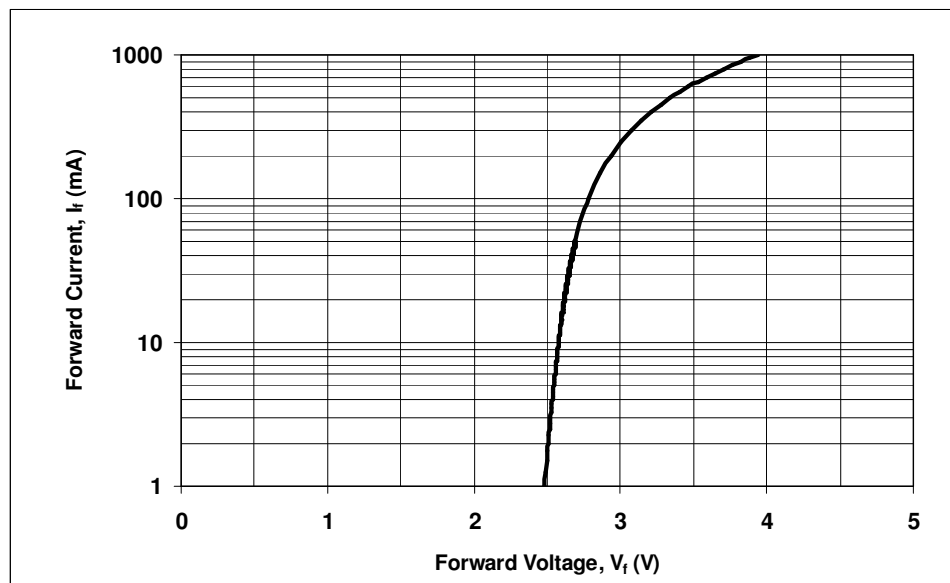


Figure 2: Forward Current vs. Forward Voltage ($T_j = 25^\circ\text{C}$)

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Performance vs. Junction Temperature

The following curves represent typical performance of the BXCD NLX-6 blue power die. Actual performance will vary slightly for different power and dominant wavelength bins.

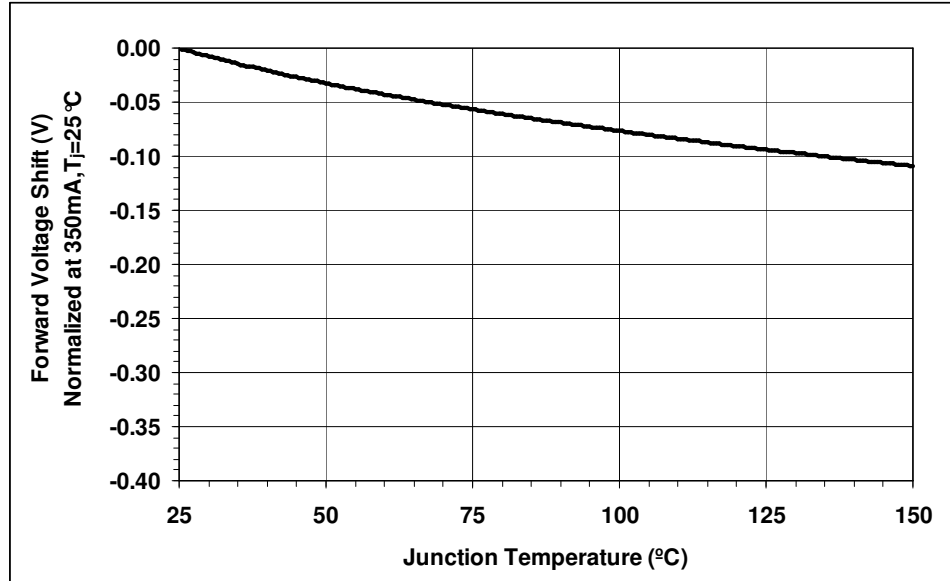


Figure 3: Forward Voltage vs. Junction Temperature

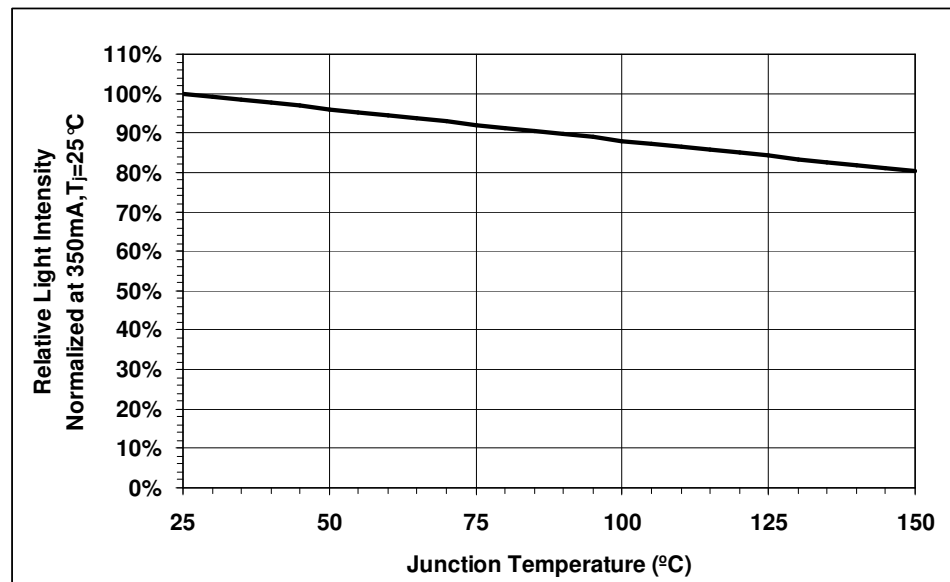


Figure 4: Relative Light Output vs. Junction Temperature

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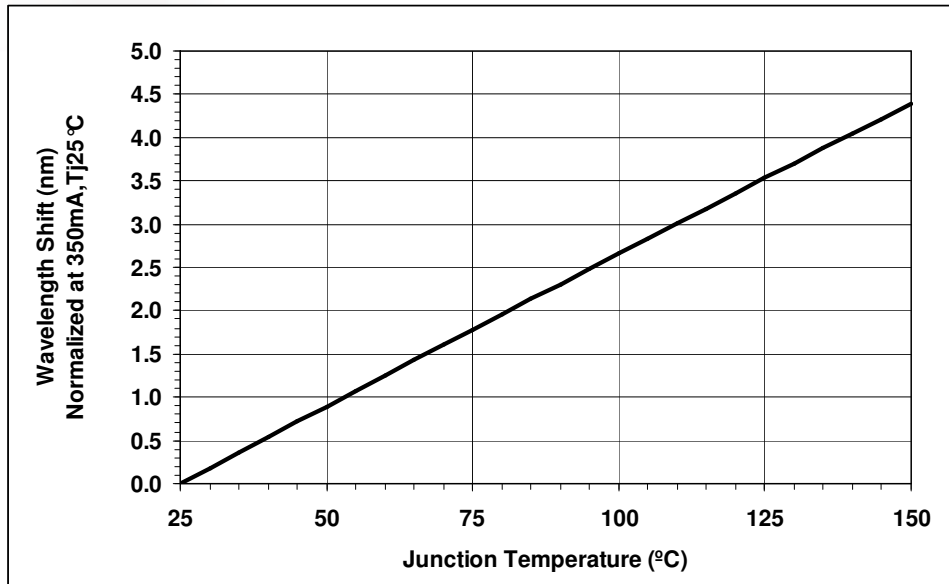


Figure 5: Wavelength Shift vs. Junction Temperature

Typical Radiation Pattern

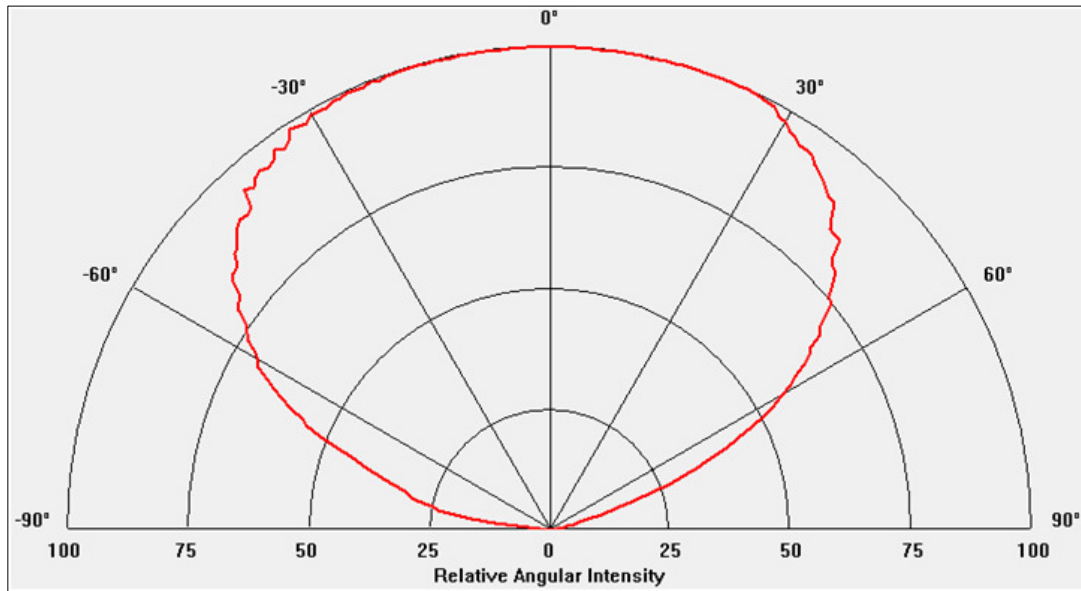


Figure 6: Typical Radiation Pattern (350 mA Operation)

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Current Derating Curves

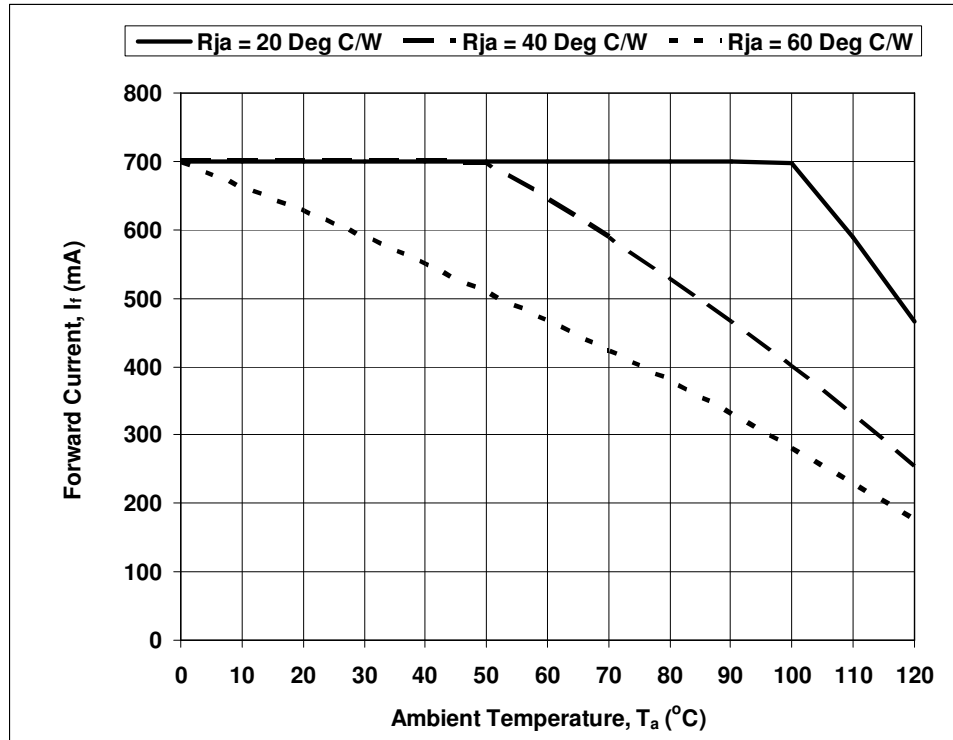


Figure 7: Current Derating Curve vs. Ambient Temperature (derating based on T_j max 150°C)

ABOUT BRIDGELUX

Bridgelux is a U.S. lighting company and leading developer of technologies and solutions that are transforming the global lighting industry. Based in Silicon Valley, Bridgelux is a pioneer in solid-state lighting (SSL), expanding the market for solid state lighting by driving down the cost of light through innovation.

The company is a leading provider of high-power, cost-effective and energy-efficient light-emitting diode (LED) solutions. Focused on bringing innovation to light, Bridgelux's proprietary epitaxy technology, advanced chip designs and leading-edge LED packaging technology have enabled the company to develop advanced solid-state lighting (SSL) products that offer superior quality, are lower in cost and environmentally friendly—all without compromising performance.

In addition to LED chips, Bridgelux's patented light source technology replaces traditional lighting technologies (such as incandescent, halogen and fluorescent lamps) with integrated, solid-state solutions, enabling lamp and luminaire manufacturers to develop high performance and energy-efficient white light products.

For more information about the company, please visit www.bridgelux.com

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